

DCR6430M22

Phase Control Thyristor

DS6034-1 April 2011 (LN28245)

FEATURES

- Double Side Cooling
- High Surge Capability

APPLICATIONS

- High Power Drives
- High Voltage Power Supplies
- Static Switches

VOLTAGE RATINGS

Part and Ordering Number	Repetitive Peak Voltages V _{DRM} and V _{RRM} V	Conditions
DCR6430M22 DCR6430M20 DCR6430M18	2200 2000 1800	$\begin{array}{l} T_{vj} = -40^{\circ}C \text{ to } 125^{\circ}C, \\ I_{DRM} = I_{RRM} = 400\text{mA}, \\ V_{DRM}, V_{RRM} t_p = 10\text{ms}, \\ V_{DSM} \& V_{RSM} = \\ V_{DRM} \& V_{RRM} + 100V \\ \text{respectively} \end{array}$

Lower voltage grades available.

ORDERING INFORMATION

When ordering, select the required part number shown in the Voltage Ratings selection table.

For example:

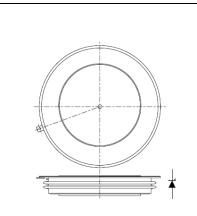
DCR6430M22

Note: Please use the complete part number when ordering and quote this number in any future correspondence relating to your order.

KEY PARAMETERS

V _{DRM}	2200 V
I _{T(AV)}	6430 A
I _{TSM}	80000 A
dV/dt*	1000 V/µs
dl/dt	250 A/µs

* Higher dV/dt selections available



Outline type code: M.

(See Package Details for further information)

Fig. 1 Package outline



CURRENT RATINGS

 $T_{case} = 60^{\circ}C$ unless stated otherwise

Symbol	Parameter	Test Conditions		Units
Double Si	de Cooled			
I _{T(AV)}	Mean on-state current	Half wave resistive load	6430	А
I _{T(RMS)}	RMS value	-	10100	А
Ι _Τ	Continuous (direct) on-state current	-	9090	А

SURGE RATINGS

Symbol	Parameter	Test Conditions	Max.	Units
I _{TSM}	Surge (non-repetitive) on-state current10ms half sine, $T_{case} = 125^{\circ}C$		80.0	kA
l ² t	I ² t for fusing	V _R = 0	32.00	MA ² s

THERMAL AND MECHANICAL RATINGS

Symbol	Parameter	Test Conditions		Min.	Max.	Units
R _{th(j-c)}	Thermal resistance – junction to case	Double side cooled	DC	-	0.005	°C/W
R _{th(c-h)}	Thermal resistance – case to heatsink	Double side cooled	DC	-	0.0015	°C/W
T_{vj}	Virtual junction temperature	Blocking V _{DRM} / _{VRRM}		-	125	°C
T _{stg}	Storage temperature range			-40	140	°C
F _m	Clamping force			80	100	kN



DYNAMIC CHARACTERISTICS

Symbol	Parameter	Test Conditions		Min.	Max.	Units
I _{RRM} /I _{DRM}	Peak reverse and off-state current	At V _{RRM} /V _{DRM} , T _{case} = 125°C		-	400	mA
dV/dt	Max. linear rate of rise of off-state voltage	To 67% V_{DRM} , $T_j = 125$ °C, gate open		1000	-	V/µs
dl/dt	Rate of rise of on-state current	From 67% V _{DRM} to 5000A	Repetitive 50Hz	-	250	A/µs
		Gate source 30V, 10Ω ,	Non-repetitive	-	1000	A/µs
		$t_r < 0.5 \mu s, T_j = 125^{\circ}C$				
V_{T}	On-state voltage	I _T = 3000A, T _{case} = 125°C			1.05	V
V _{T(TO)}	Threshold voltage	T _{case} = 125°C		-	0.87	V
r _T	On-state slope resistance	T _{case} = 125°C		-	0.061	mΩ
t _{gd}	Delay time	V_D = 67% V_{DRM} , gate source 30V, 10 Ω t_r = 0.5µs, T _j = 25°C		-	3.0	μs
tq	Turn-off time	T_j = 125°C, V _R = 100V, dl/dt = 1.5A/µs,		-	500	μs
		$dV_{DR}/dt = 20V/\mu s$ linear to 67% V_{DRM}				
Qs	Stored charge	$I_{T} = 2000A, tp = 1000us, T_{j} = 125^{\circ}C, \\ dI/dt = 1.5A/\mu s,$		-	3000	μC
I _{RR}	Reverse recovery current			-	75	А
١	Latching current	$T_j = 25^{\circ}C,$		-	1	А
I _H	Holding current	$T_j = 25^{\circ}C,$		-	200	mA

GATE TRIGGER CHARACTERISTICS AND RATINGS

Symbol	Parameter	Test Conditions	Max.	Units
V _{GT}	Gate trigger voltage	$V_{DRM} = 5V, T_{case} = 25^{\circ}C$	3	V
V_{GD}	Gate non-trigger voltage	At 40% V _{DRM} , T _{case} = 125°C	TBD	V
I _{GT}	Gate trigger current	$V_{DRM} = 5V, T_{case} = 25^{\circ}C$	300	mA
I _{GD}	Gate non-trigger current	At 40% V _{DRM,} T _{case} = 125°C	TBD	mA



CURVES

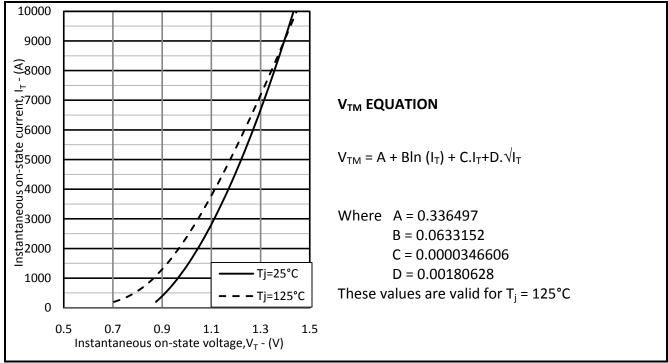


Fig.2 Maximum & minimum on-state characteristics

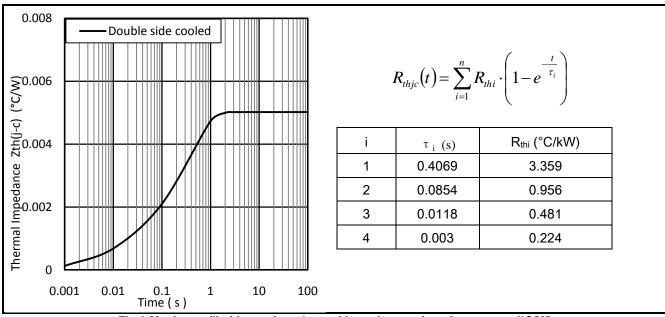


Fig.3 Maximum (limit) transient thermal impedance – junction to case (°C/W)



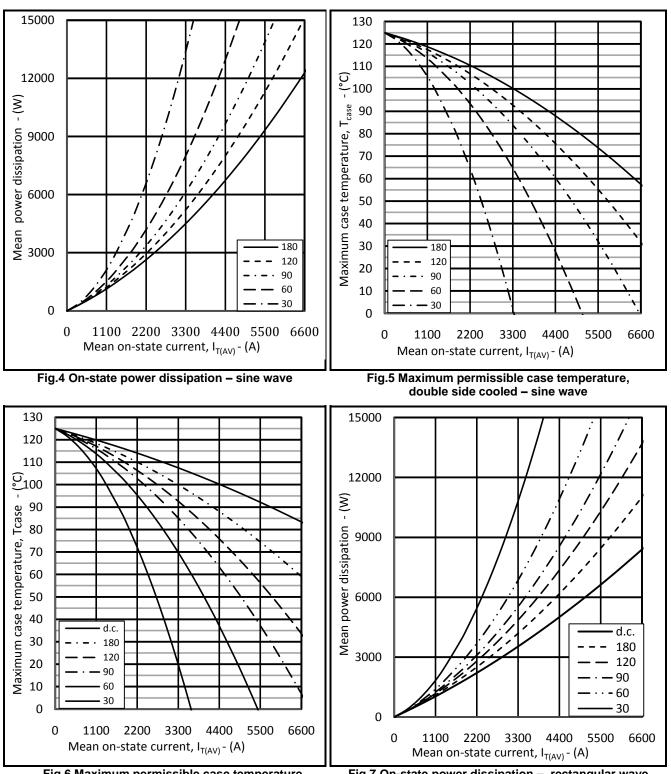
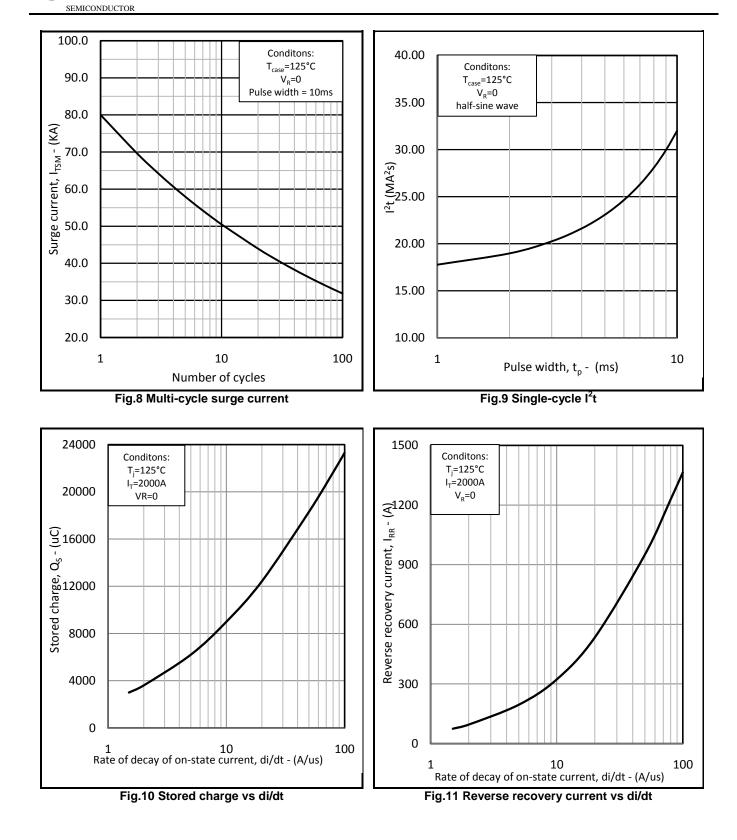


Fig.6 Maximum permissible case temperature, double side cooled – rectangular wave







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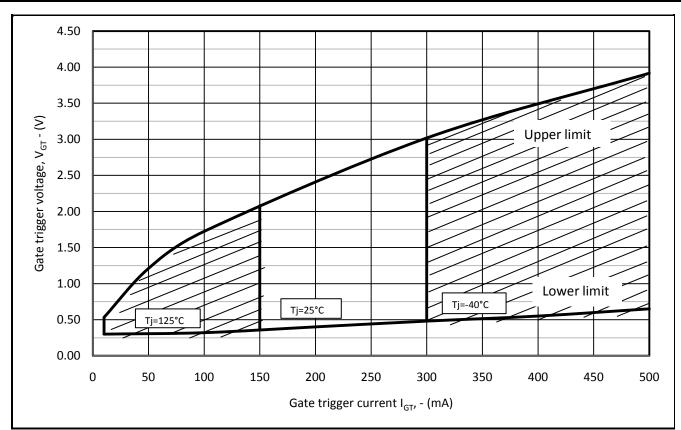


Fig.12 Gate characteristics

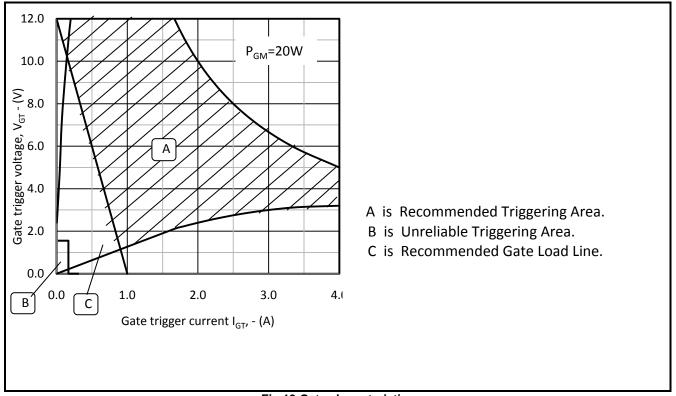


Fig.13 Gate characteristics

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PACKAGE DETAILS

For further package information, please contact Customer Services. All dimensions in mm, unless stated otherwise. DO NOT SCALE.

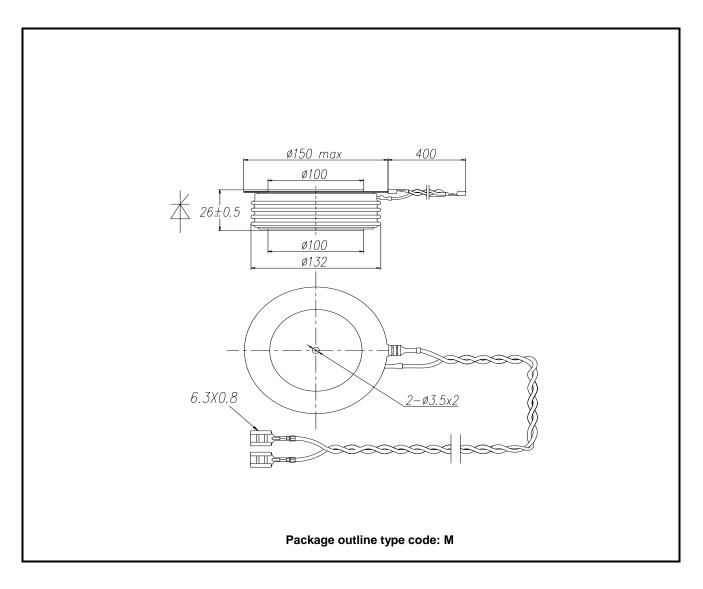


Fig.14 Package outline



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